

AMENDMENTS

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-111 Previously Canceled

112. (Original) A chip socket assembly comprising:

a chip package having a contact side, the contact side comprising a plurality of compliant contacts, the contacts adapted for detachable electrical coupling to a circuit board, the chip package having second and third sides formed with oppositely disposed protrusions; an integrated circuit disposed within the chip package, the integrated circuit electrically coupled to the plurality of compliant contacts; and

a base formed with oppositely disposed clip portions to receive the chip package, the clip portions formed with sockets to detachably engage the chip package protrusions.

113. (Original) The chip socket assembly of claim 112, wherein the contacts are adapted for direct engagement to the circuit board.

114. (Original) The chip socket assembly of claim 112, further including an elastomeric connector, the elastomeric connector interposed between the circuit board and the base, and wherein the contacts are adapted for engaging the elastomeric connector.

115. (Original) The chip socket assembly of claim 114, wherein the contacts are compressible and the elastomeric connector is cylindrical, providing spring force when the contacts are compressed.

116. (Original) The chip socket assembly of claim 112, wherein the contacts are compressible and the contact side of the chip package is extended to form a pocket into which the contacts extend when compressed.

117. (Original) The chip socket assembly of claim 112, further comprising:
a pin extending from the chip package; and

a slotted guide in the base configured to receive the pin and guide the chip package into the base.

118. (Original) The chip socket assembly of claim 112, wherein the contacts are substantially C-shaped.

119. (Original) The chip socket assembly of claim 112, wherein the contacts comprise beryllium-copper.

120. (Original) The chip socket assembly of claim 112, wherein the chip package comprises a flexible material.

121. (Original) The chip socket assembly of claim 112, wherein the chip package comprises silicone rubber.

122. (Original) The chip socket assembly of claim 112, wherein the integrated circuit is flexible.

INTERVIEW

On July 19, 2005 the Applicants conducted a telephone interview with the Examiner. Applicants presented various arguments distinguishing the present claims over the prior art. No resolution was reached.